

CLAIMS

1. A method of peeling a semiconductor chip,
comprising the steps of:

5 peeling a semiconductor chip adhered to a
tape from said tape by a peeling device including a
plurality of annular contact members arranged one after
another from the outside to the inside, wherein the
plurality of annular contact members are operated so
that the semiconductor chip is successively peeled off
10 from the tape from an outer circumferential portion
thereof toward a central portion thereof.

2. The method of peeling a semiconductor chip
according to claim 1, wherein the plurality of annular
contact members are simultaneously moved, and then, the
15 outermost annular contact member in the plurality of
annular contact members is stopped and the remaining
annular contact members are further moved
simultaneously.

3. A device for peeling a semiconductor chip
20 adhered to a tape off from said tape, comprising:

 a plurality of annular contact members
arranged one after another from the outside to the
inside; and

 an operation device for operating the
25 plurality of annular contact members so that the
semiconductor chip is successively peeled, from the
tape, from an outer circumferential portion thereof to a
central portion thereof.

4. The device for peeling a semiconductor chip
30 according to claim 3, wherein the operation device
includes a cam for operating the plurality of annular
contact members.

5. The device for peeling a semiconductor chip according to claim 3, further comprising a frame defining a vacuum chamber therein, a top plate arranged on said frame and having an opening, and a suction
5 device arranged above said frame, said annular contact members being arranged in said frame.